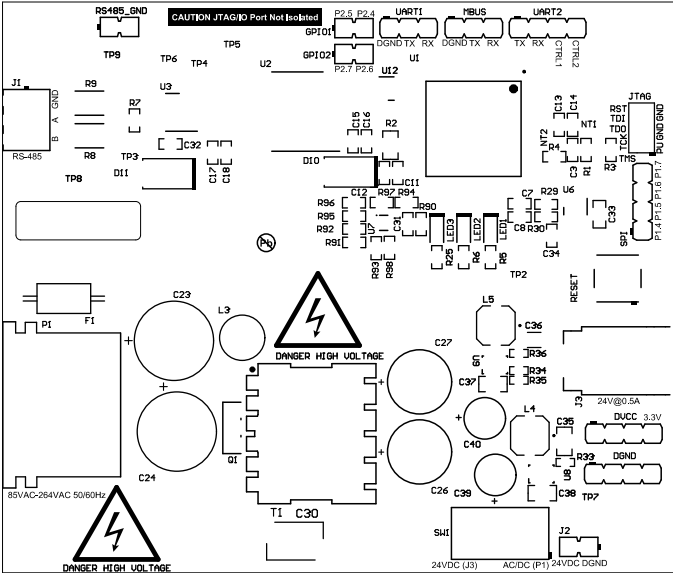
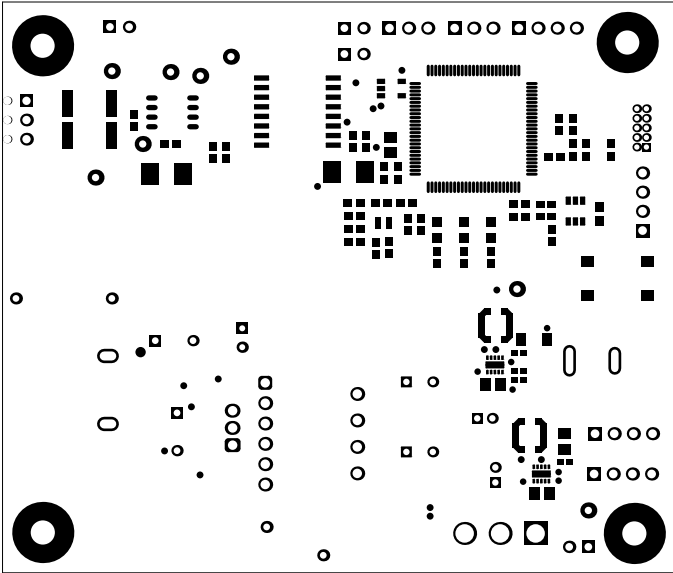


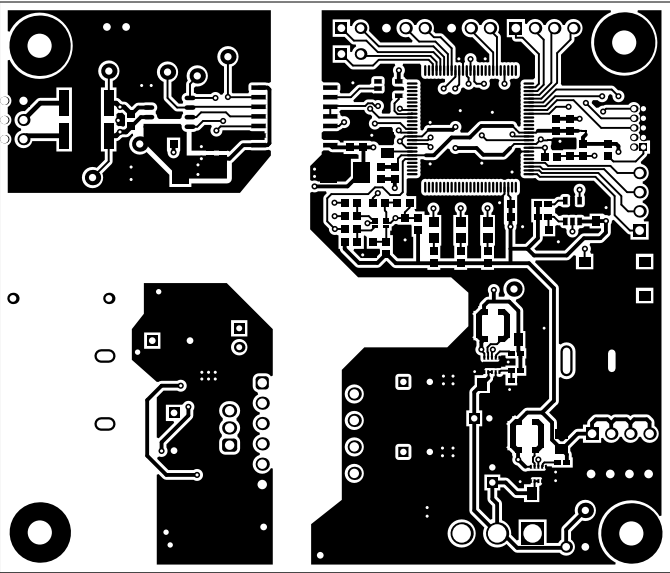


F101 F102 F103

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-1005	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDM-1005		
PLOT NAME = Top Overlay	GENERATED : 5/11/2017 4:12:23 PM	TEXAS INSTRUMENTS	

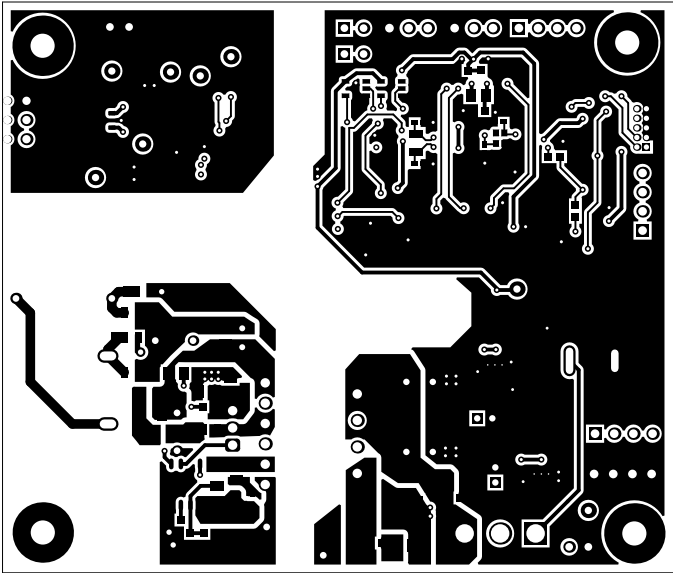


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-1005	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDM-1005		
PLOT NAME = Top Solder Mask	GENERATED : 5/11/2017 4:12:24 PM	TEXAS INSTRUMENTS	



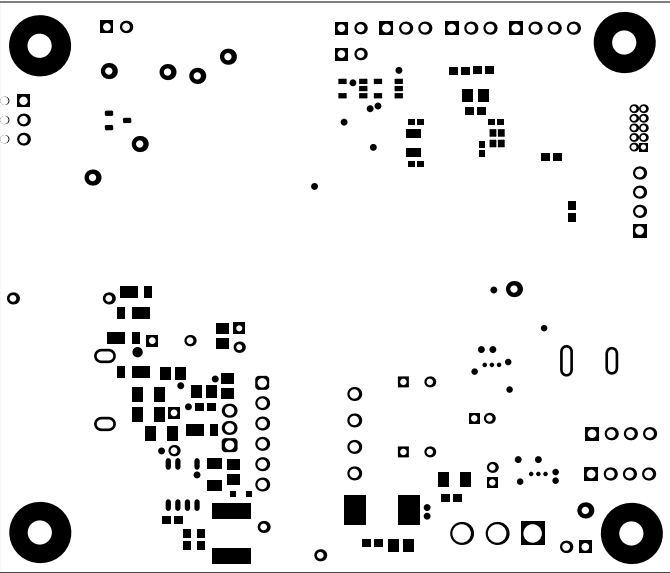
. . .

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-1005	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDM-1005		
PLOT NAME = Top Layer	GENERATED : 5/11/2017	4:12:25 PM	TEXAS INSTRUMENTS



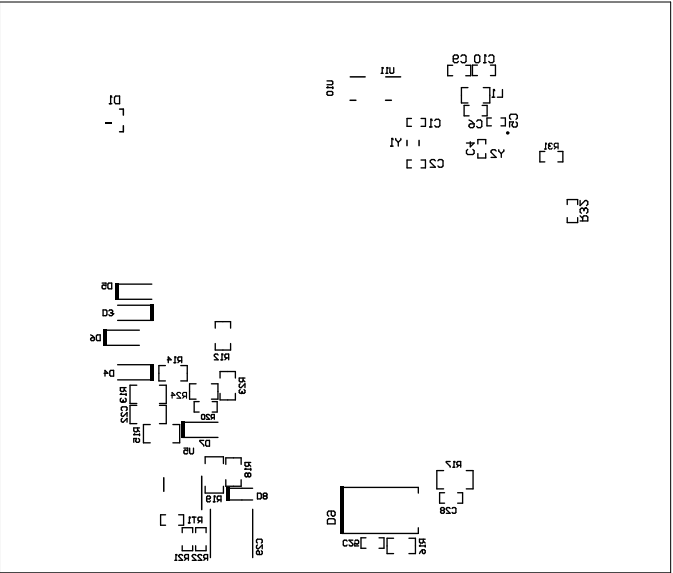
...

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-1005	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDM-1005		
PLOT NAME = Bottom Layer	GENERATED : 5/11/2017	4:12:26 PM	TEXAS INSTRUMENTS

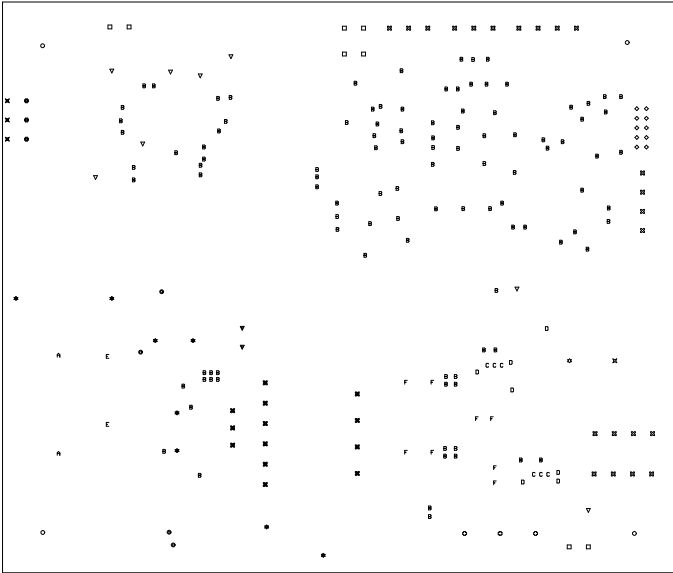


...

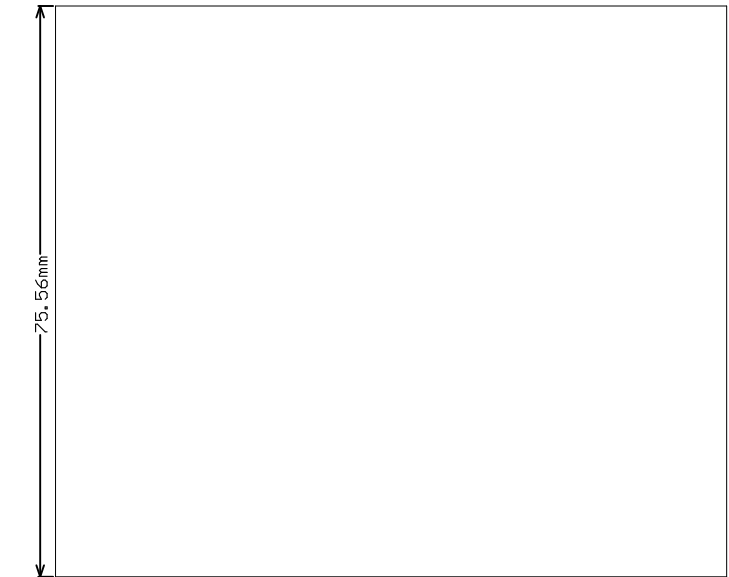
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-1005	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDM-1005		
PLOT NAME = Bottom Solder Mask	GENERATED : 5/11/2017 4:12:27 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-1005	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDM-1005		
PLOT NAME = Bottom Overlay	GENERATED : 5/11/2017 4:12:28 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-1005	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDM-1005		
PLOT NAME = Drill Drawing	GENERATED : 5/11/2017	4:12:29 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-1005	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDM-1005		
PLOT NAME = Board Dimensions	GENERATED : 5/11/2017 4:12:31 PM	TEXAS INSTRUMENTS	

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